

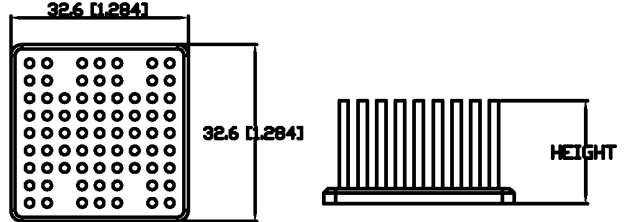
Model : MBA33002 Series



BGA Heat Sink Specification

For 33x33 Chip set

- 1. Material : Al 6063
- 2. Dimension :
 - Foot print : 33x33mm
 - Height : 12,15,18,21,23,28,33 mm
 - Base (thickness) : 2.6mm



- 3. Finish: Black Anodize
- 4. Chip set package thickness and clip color
 - 3.3+/-0.25mm - Yellow clip
 - 1.7+/-0.25mm - Blue clip
 - 0.8+/-0.25mm - Orange clip
- 5. Accessory :
 - Clip : Plastic (UL94-V0)
 - Thermal pad : T710 or others



Performance

Heat Source (LxW)	15x15
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